

**描述 / Descriptions**

PDFN5×6 封装 N 沟道场效应管。

N-Channel MOSFET in a PDFN5×6 Plastic Package .

**特征 / Features**

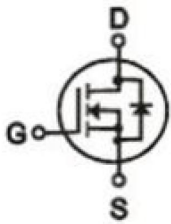
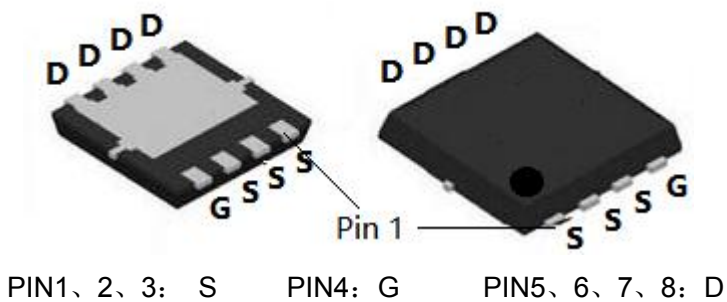
低电阻可最大地降低导电损耗；低栅极电荷，可实现快速切换；低热阻；无卤产品。

Low  $R_{DS(ON)}$  to minimize conductive loss; low Gate Charge for fast switching; Low Thermal resistance; HF Product.

**用途 / Applications**

电池管理，MB/NB/UMPC/VGA 高频负载点同步 Buck 变换器，联网直流-直流电力系统，负荷开关。

Battery Management, High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA, Networking DC-DC Power System, Load Switch.

**内部等效电路 / Equivalent Circuit****引脚排列 / Pinning**

Pin	极性
1	S
2	S
3	S
4	G
5	D
6	D
7	D
8	D

**印章代码 / Marking**

见印章说明。

See Marking Instructions.

**极限参数 / Absolute Maximum Ratings( $T_a=25^{\circ}\text{C}$ )**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	$V_{DS}$	100	V
Drain Current - Continuous	$I_D$	168	A
Drain Current – Pulsed	$I_{DM}$	400	A
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Power Dissipation	$P_D(T_c=25^{\circ}\text{C})$	215	W
Single Pulse Avalanche Energy(L=0.5mH)	$E_{AS}$	563	mJ
Avalanche Current(L=0.5mH)	$I_{AS}$	37.5	A
Junction and Storage Temperature Range	$T_j, T_{stg}$	-55 to 150	$^{\circ}\text{C}$
Thermal resistance, junction - ambient	$t \leq 10\text{s}$	$R_{\theta JA}$	$^{\circ}\text{C/W}$
	Steady-State		
Thermal resistance, junction - case	Steady-State	$R_{\theta JC}$	0.58

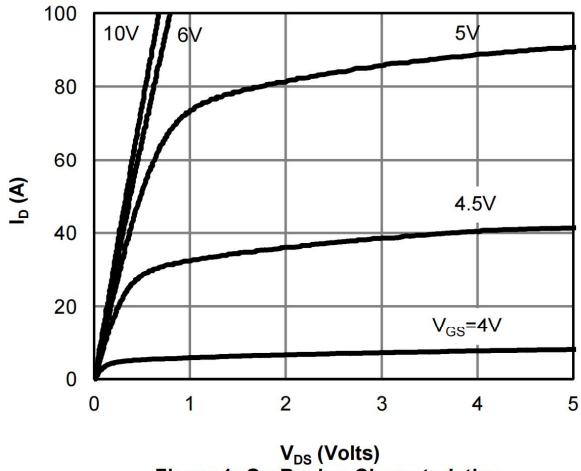
**电性能参数 / Electrical Characteristics( $T_a=25^{\circ}\text{C}$ )**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	100	112		V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=100\text{V}, V_{GS}=0\text{V}$			1	$\mu\text{A}$
Gate-Body leakage current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2	2.9	4	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}, I_D=20\text{A}$		3.5	4.0	$\text{m}\Omega$
Diode Forward Voltage	$V_{SD}$	$I_S=1\text{A}, V_{GS}=0\text{V}$			1.2	V
Input Capacitance	$C_{iss}$	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$		5550		$\text{pF}$
Output Capacitance	$C_{oss}$			2050		
Reverse Transfer Capacitance	$C_{rss}$			180		
Gate resistance	$R_g$	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		1.7		$\Omega$
Total Gate Charge	$Q_{g(10V)}$	$V_{GS}=10\text{V}, V_{DS}=50\text{V}, I_D=20\text{A}$		70		nC
Gate Source Charge	$Q_{gs}$			20		
Gate Drain Charge	$Q_{gd}$			10		

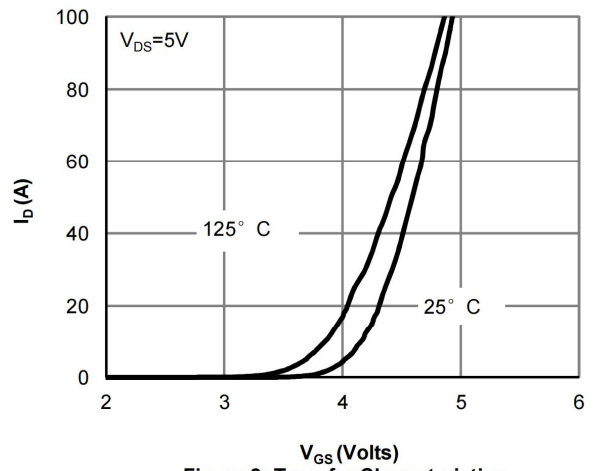
## 电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V$ $V_{DS}=50V$ $R_L=2.5\Omega$ $R_{GEN}=3\Omega$		19		ns
Turn-On Rise Time	$t_r$			8		
Turn-Off Delay Time	$t_{d(off)}$			32		
Turn-Off Fall Time	$t_f$			11		

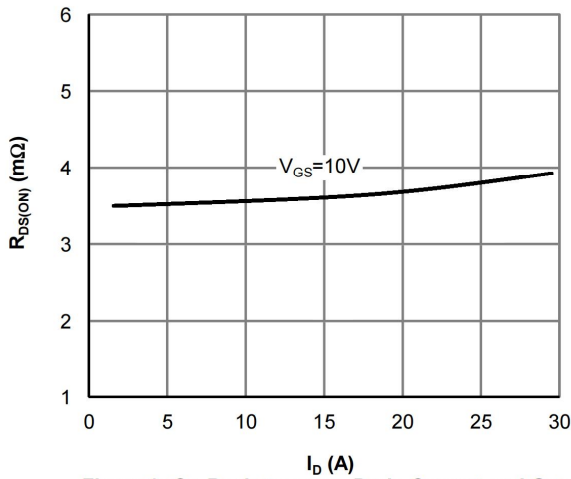
**电参数曲线图 / Electrical Characteristic Curve**



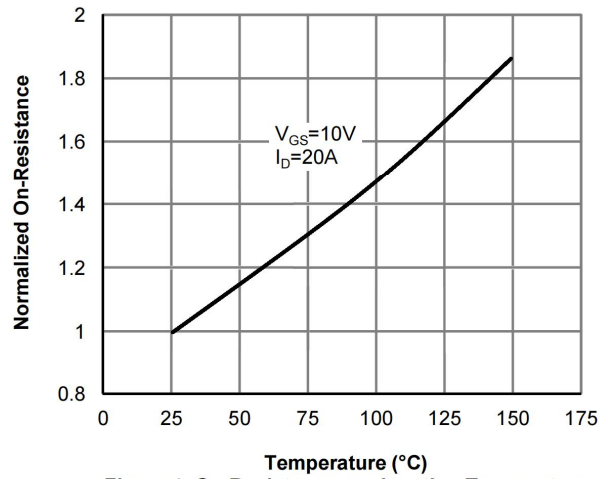
**Figure 1: On-Region Characteristics**



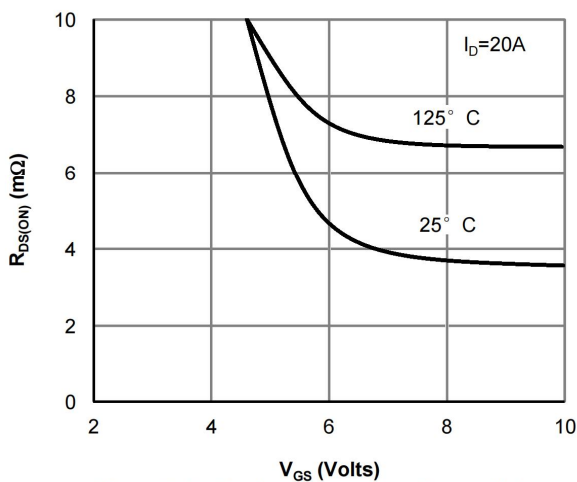
**Figure 2: Transfer Characteristics**



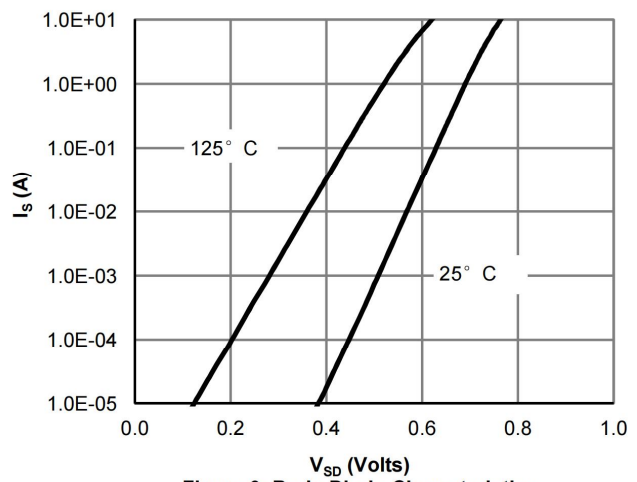
**Figure 3: On-Resistance vs. Drain Current and Gate Voltage**



**Figure 4: On-Resistance vs. Junction Temperature**

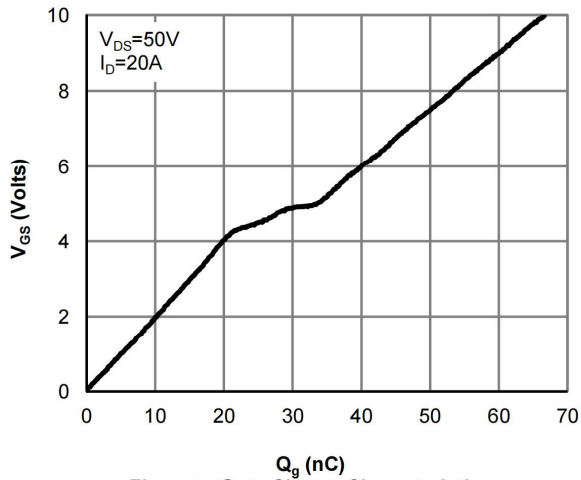


**Figure 5: On-Resistance vs. Gate-Source Voltage**

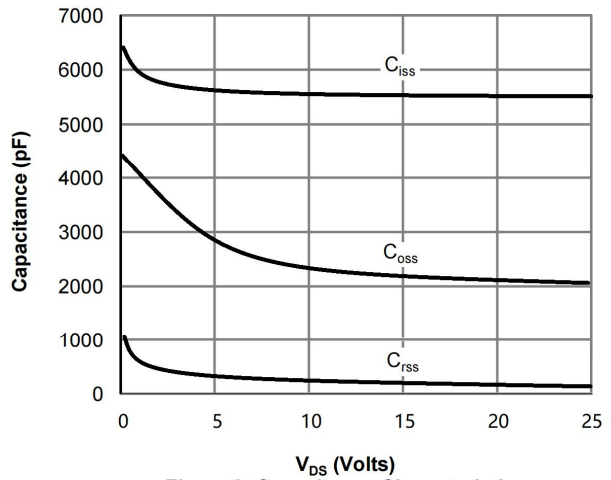


**Figure 6: Body-Diode Characteristics**

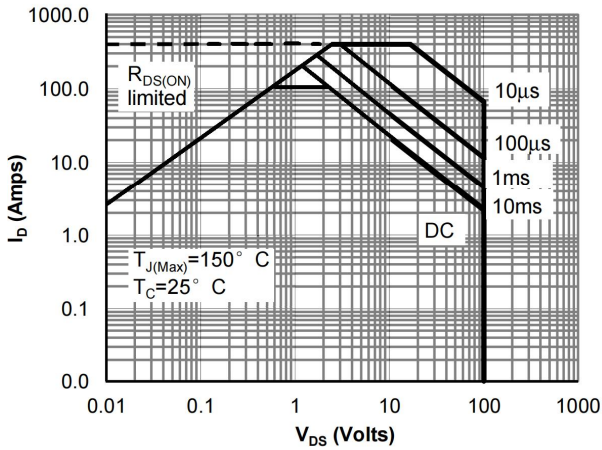
**电参数曲线图 / Electrical Characteristic Curve**



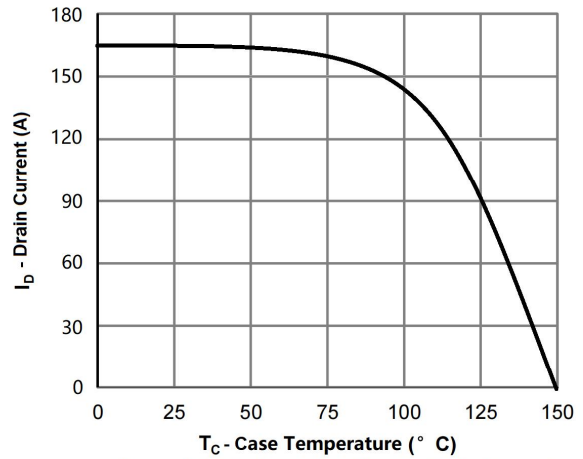
**Figure 7: Gate-Charge Characteristics**



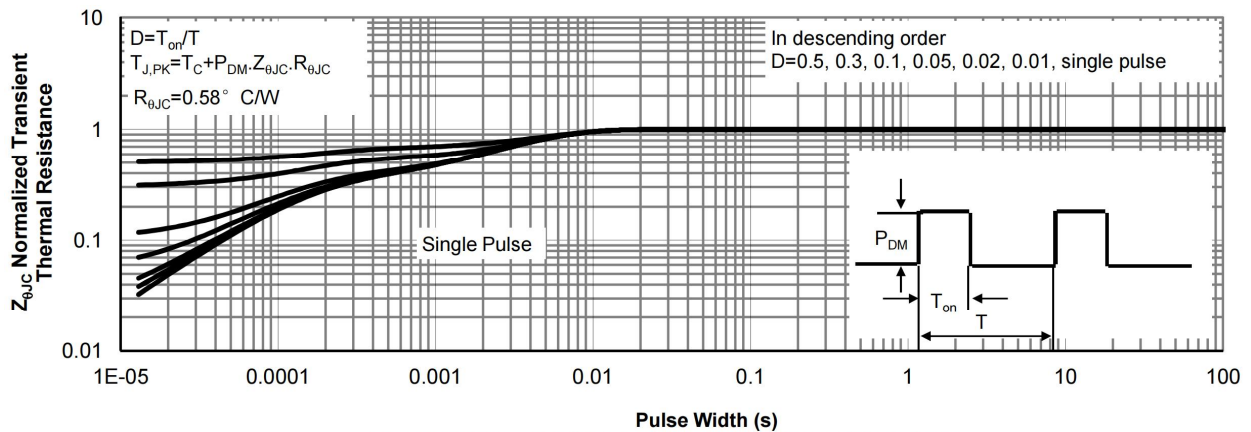
**Figure 8: Capacitance Characteristics**



**Figure 9: Maximum Forward Biased Safe Operating Area**



**Figure 10: Maximum Continuous Drain Current vs Case Temperature**

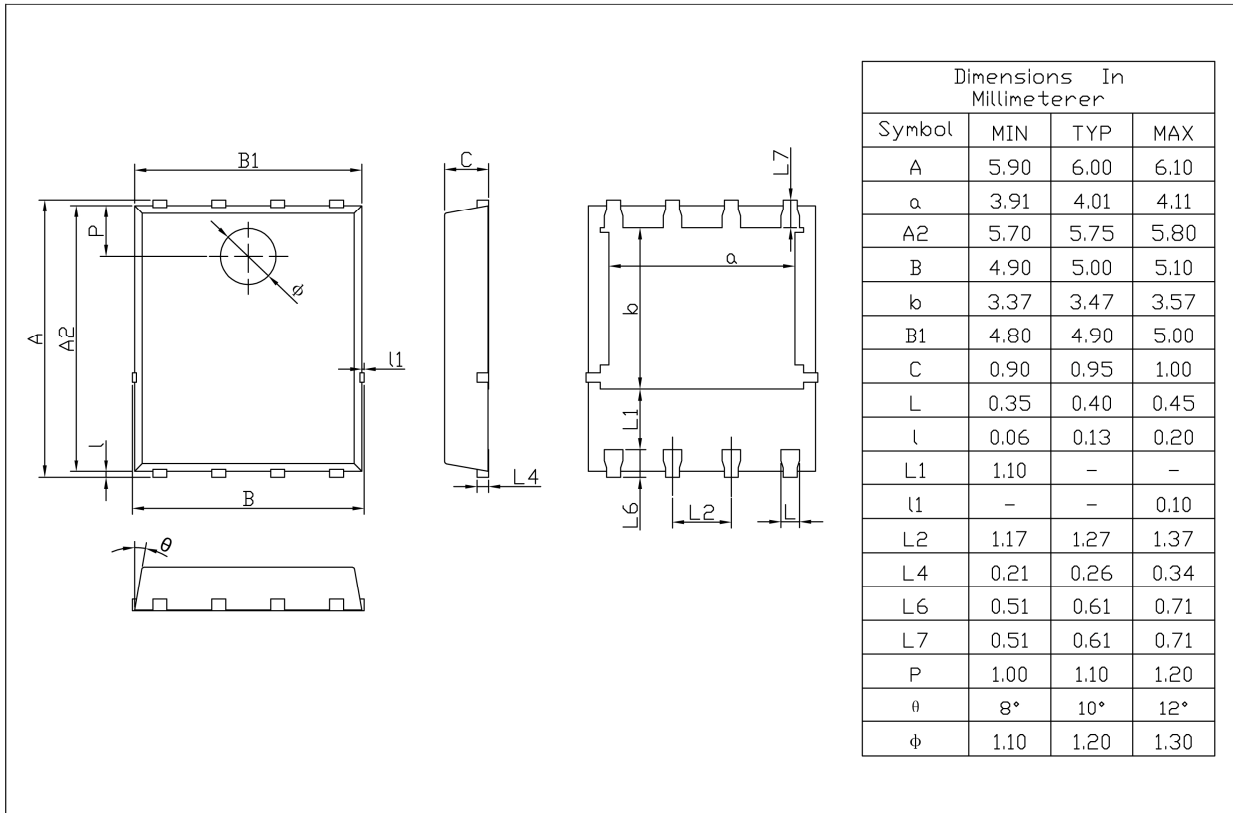


**Figure 11: Normalized Maximum Transient Thermal Impedance**

**外形尺寸图 / Package Dimensions**

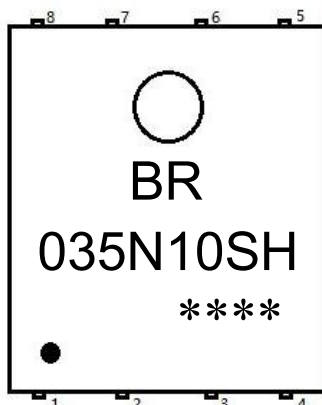
PDFN5 X6

Unit:mm



Rev.00 201812

**印章说明 / Marking Instructions**



说明：

BR： 为公司代码

035N10SH： 为为产品型号

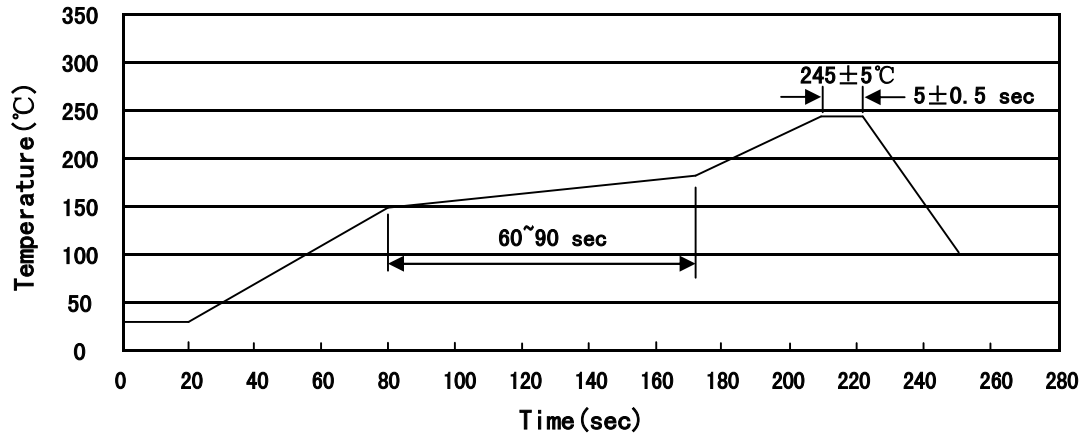
\*\*\*\*： 为生产批号代码，随生产批号变化

Note：

BR： Company Code

035N10SH： Product Type

\*\*\*\*： Lot No. Code, code change with Lot No

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
PDFN5 × 6	5000	2	10000	6	60000	13" × 12	360 × 360 × 50	380 × 335 × 366

**使用说明 / Notices**